

Title (en)

PRINTED CIRCUIT BOARD ASSEMBLY AND METHOD FOR PRODUCING A PRINTED CIRCUIT BOARD ASSEMBLY

Title (de)

LEITERPLATTEN-ANORDNUNG SOWIE VERFAHREN ZUR HERSTELLUNG EINER LEITERPLATTEN-ANORDNUNG

Title (fr)

SYSTÈME DE PLAQUES Á CIRCUITS IMPRIMÉS AINSI QUE PROCÉDÉ DE FABRICATION D'UN SYSTÈME DE PLAQUES Á CIRCUITS IMPRIMÉS

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Application

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Abstract (en)

[origin: WO2018188918A1] The invention relates to a printed circuit board assembly (1) for an electronic circuit. The printed circuit board assembly (100) comprises a first printed circuit board (110) having one or more electrically conductive first contact points (111) on a front side (114) of the first printed circuit board (110). In addition, the printed circuit board assembly (100) comprises a second printed circuit board (120) having one or more electrically conductive second contact points (121) on a rear side (123) of the second printed circuit board (120). The printed circuit board assembly (100) also comprises a spacer element (130) having one or more conductor tracks (134) on a rear side of the spacer element (130) and having one or more conductor tracks (134) on a front side of the spacer element (130). The one or more conductor tracks (134) on the rear side is/are connected to the one or more conductor tracks (134) on the front side in an electrically conductive manner. Furthermore, the one or more conductor tracks (134) on the rear side is/are soldered to the one or more first contact points (111). In addition, the one or more conductor tracks (134) on the front side is/are soldered to the one or more second contact points (121).

IPC 8 full level

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Citation (search report)

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